

October 2013

# RURD660S9A\_F085 Ultrafast Power Rectifier, 6A 600V

#### **Features**

- High Speed Switching (t<sub>rr</sub>=63ns(Typ.) @ I<sub>F</sub>=6A)
- Low Forward Voltage( V<sub>F</sub>=1.26V(Typ.) @ I<sub>F</sub>=6A )
- · Avalanche Energy Rated
- · AEC-Q101 Qualified

## **Applications**

- · General Purpose
- · Switching Mode Power Supply
- · Power switching circuits

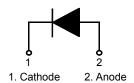
#### 6A, 600V Ultrafast Rectifier

The RURD660S9A\_F085 is an ultrafast diode with soft recovery characteristics (trr< 83ns). It has a low forward voltage drop and is of silicon nitride passivated ionimplanted epitaxial planar construction. This device is intended for use as a freewheeling/clamping diode and rectifier in a variety of switching power supplies and other power switching applications. Its low stored charge and ultrafast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing powerloss in the switching transistors.

## **Pin Assignments**



1. Cathode 2. Anode



## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

| Symbol                           | Parameter   | Ratings      | Units |  |
|----------------------------------|---|--------------|-------|--|
| V <sub>RRM</sub>                 | Peak Repetitive Reverse Voltage                           | 600          | V     |  |
| V <sub>RWM</sub>                 | Working Peak Reverse Voltage                              | 600          | V     |  |
| V <sub>R</sub>                   | DC Blocking Voltage                                       | 600          | V     |  |
| I <sub>F(AV)</sub>               | Average Rectified Forward Current @ T <sub>C</sub> = 25°C | 6            | Α     |  |
| I <sub>FSM</sub>                 | Non-repetitive Peak Surge Current                         | 60           | Α     |  |
| T <sub>J,</sub> T <sub>STG</sub> | Operating Junction and Storage Temperature                | - 55 to +175 | °C    |  |

#### Thermal Characteristics T<sub>C</sub> = 25°C unless otherwise noted

| Symbol                         | Parameter                                       | Max | Units |
|--------------------------------|---|-----|-------|
| $R_{\theta JC}$                | Maximum Thermal Resistance, Junction to Case    | 3   | °C/W  |
| R <sub>0JA</sub> 1             | Maximum Thermal Resistance, Junction to Ambient | 140 | °C/W  |
| R <sub>0 IA</sub> <sup>2</sup> | Maximum Thermal Resistance, Junction to Ambient | 50  | °C/W  |

## **Package Marking and Ordering Information**

| Device Marking Device |                 | Package   | Tube | Quantity |  |
|-----------------------|-----------------|-----------|------|----------|--|
| RUR660                | RURD660S9A_F085 | TO-252-2L | -    | 60       |  |

#### Notes:

- 1. Mounted on a minimum pad follow by JEDEC standard.
- 2. Mounted on a 1 in 2 pad of 2 oz copper follow by JEDEC standard.

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted

| Symbol  | Parameter                                     | Conditions   |   | Min.        | Тур.            | Max         | Units          |
|---|---|--|---|-------------|-----------------|-------------|----------------|
| I <sub>R</sub>                                      | Instantaneous Reverse Current                 | V <sub>R</sub> = 600V  | T <sub>C</sub> = 25 °C                            | -           | -               | 100         | uA             |
|   |   |  | T <sub>C</sub> = 175 °C                           | -           | -               | 500         | uA             |
| V <sub>FM</sub> <sup>3</sup>                        | Instantaneous Forward Voltage                 | I <sub>F</sub> = 6A  | T <sub>C</sub> = 25 °C<br>T <sub>C</sub> = 175 °C | -           | 1.26<br>1.04    | 1.5<br>-    | V<br>V         |
| t <sub>rr</sub> <sup>4</sup>                        | Reverse Recovery Time                         | I <sub>F</sub> =1A, di/dt = 200A/μs,<br>V <sub>CC</sub> = 390V | T <sub>C</sub> = 25 °C                            | -           | 25              | 33          | ns             |
|   |   | $I_F$ =6A, di/dt = 200A/ $\mu$ s, $V_{CC}$ = 390V              | T <sub>C</sub> = 25 °C<br>T <sub>C</sub> = 175 °C | -           | 63<br>119       | 83          | ns<br>ns       |
| t <sub>a</sub><br>t <sub>b</sub><br>Q <sub>rr</sub> | Reverse Recovery Time Reverse Recovery Charge | $I_F$ =6A, di/dt = 200A/ $\mu$ s,<br>V <sub>CC</sub> = 390V    | T <sub>C</sub> = 25 °C                            | -<br>-<br>- | 23<br>40<br>151 | -<br>-<br>- | ns<br>ns<br>nC |
| W <sub>AVL</sub>                                    |   | Avalanche Energy (L = 20mH)                                    |   | 10          | -               | -           | mJ             |

#### Notes:

- 3. Pulse : Test Pulse width =  $300\mu$ s, Duty Cycle = 2%
- 4. Guaranteed by design

### **Test Circuit and Waveforms**

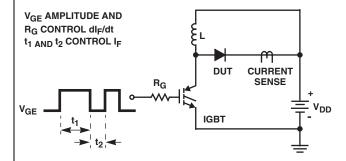


FIGURE 8. trTEST CIRCUIT

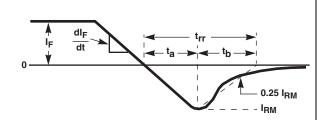


FIGURE 9. ‡ WAVEFORMS AND DEFINITIONS

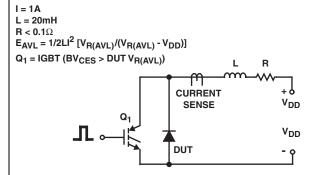


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

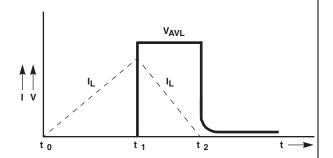


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

## **Typical Performance Characteristics**

Figure 1. Typical Forward Voltage Drop vs. Forward Current

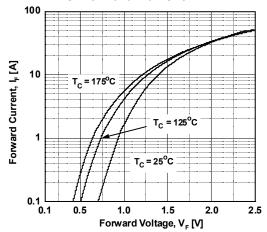


Figure 3. Typical Junction Capacitance

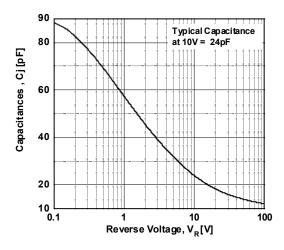


Figure 5. Typical Reverse Recovery Current vs. di/dt

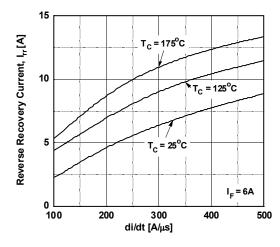


Figure 2. Typical Reverse Current vs.

Reverse Voltage

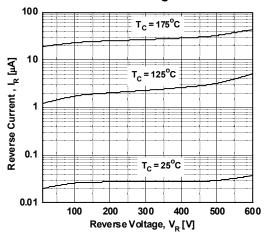


Figure 4. Typical Reverse Recovery Time vs. di/dt

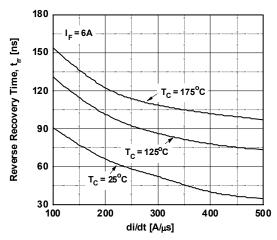
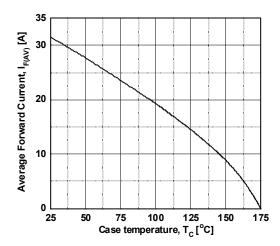


Figure 6. Forward Current Derating Curve



## **Typical Performance Characteristics** (Continued)

Figure 7. Reverse Recovery Charge

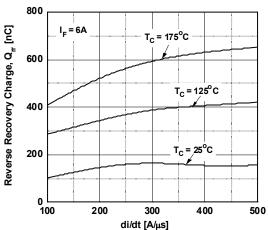
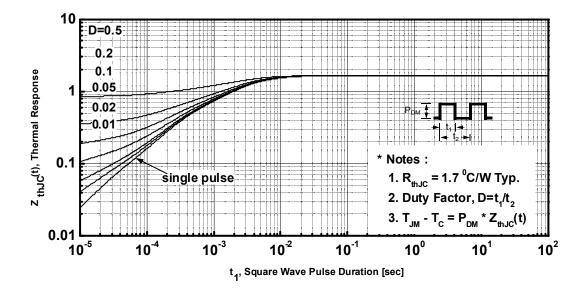
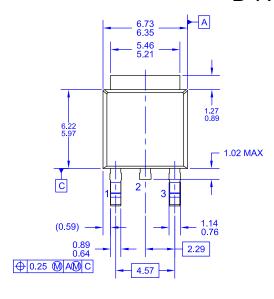


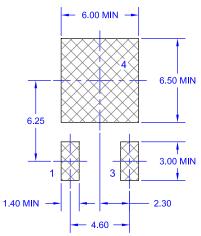
Figure 8. Transient Thermal Response Curve



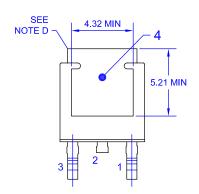
## **Mechanical Dimensions**

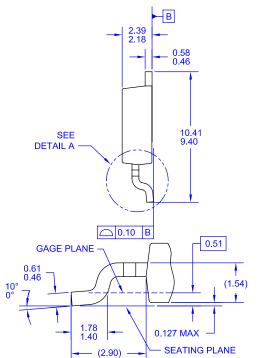
## **D-PAK**





LAND PATTERN RECOMMENDATION





- NOTES: UNLESS OTHERWISE SPECIFIED
  A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
  B) ALL DIMENSIONS ARE IN MILLIMETERS.
  C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
  D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
  E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL
- E) PRESENCE OF TRIMMED CENTER LEAD IS OPTIONAL.

  F) DIMENSIONS ARE EXCLUSSIVE OF BURSS, MOLD FLASH AND TIE BAR EXTRUSIONS.

  G) LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD TO220P1003X238-3N.

  H) DRAWING NUMBER AND REVISION: MKT-TO252A03REV8

**Dimensions in Millimeters** 





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